

TO: Examiner Mohammad Ali, art unit 3744  
RE: Proposed claim amendments to 10/028,860  
FROM: Glen Choi, Reg. No. 43,546

Enclosed are proposed claim amendments.

1. (Amended) An integrated circuit package comprising:
  - an integrated circuit die having an active surface; and
  - a cooling fluid to move laterally across and in contact with the active surface.
8. (Three Times Amended) A method of forming an integrated circuit package comprising:
  - attaching an interposer to a package substrate;
  - attaching an integrated circuit die to the interposer, wherein the integrated circuit die includes an active region;
  - covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;
  - filling the internal chamber with a cooling fluid, wherein the cooling fluid contacts a region between the interposer and the integrated circuit die and wherein the cooling fluid contacts and is to move laterally across the active region.
12. (Amended) A method of cooling an integrated circuit die within an integrated circuit package comprising:
  - providing power to the integrated circuit die; and
  - moving a cooling fluid laterally across and in contact with an active surface of the integrated circuit die.
17. (Twice Amended) An integrated circuit package comprising:
  - a package substrate;

a first integrated circuit die having an active surface;  
an interposer disposed between the package substrate and the first integrated circuit die, the interposer establishing electrical connectivity between the first integrated circuit die and the package substrate; and  
a cooling fluid disposed between the first integrated circuit die and the interposer, wherein the cooling fluid is to move laterally across and in contact with contacts the active surface.

27. (Twice Amended) An integrated circuit package comprising:
- a integrated circuit die housed within a chamber, wherein the integrated circuit die includes an active region; and  
a cooling fluid filling the chamber and in contact with and to move laterally across the active region of the integrated circuit die.